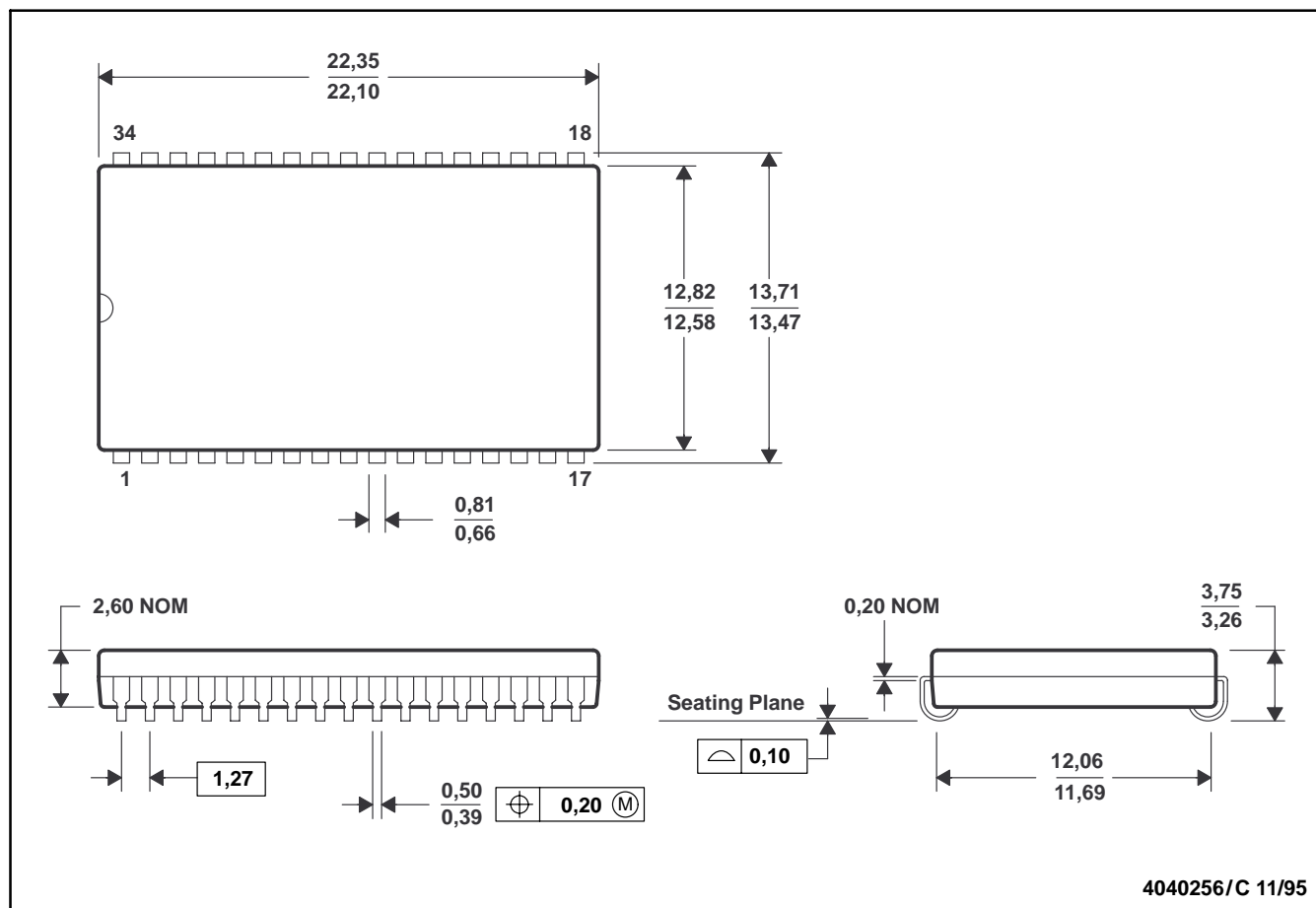


DBG (R-PDSO-J34)

PLASTIC SMALL-OUTLINE J-LEAD PACKAGE



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Plastic body dimensions do not include mold protrusion. Maximum mold protrusion is 0.28.

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